

Abstract

The present disclosure relates to burn-in apparatus, transfer method, burn-in chamber, and interchangeable frame thereof for semiconductor devices burn-in process. The burn-in apparatus comprises a burn-in chamber with an incomplete base which is to be completed and thermally insulated in cooperation with a thermal insulation base of at least one interchangeable frame which is to be removably moved into and docked in the chamber to complete the burn-in apparatus. Cooperating alignment elements are respectively arranged at the frame and the chamber, and configured to progressively and movably couple to each other to lift the frame to bring a set of burn-in boards that are supported on the frame into alignment for insertion into a set of receiving connectors in the chamber. Cooperating thermal insulation side elements may be respectively arranged at the frame and the chamber, and include complementary characteristics configured to provide a clearance gap between the thermal insulation side elements when they partially overlap each other and an abutting fit when they substantially or fully overlap each other.

Figure 4D